


Drawing No.	*Rev.	Date	Page
CBL0805A-ZBN-020mA	A	2023/02/17	1/10

APPROVAL SHEET

Part No:

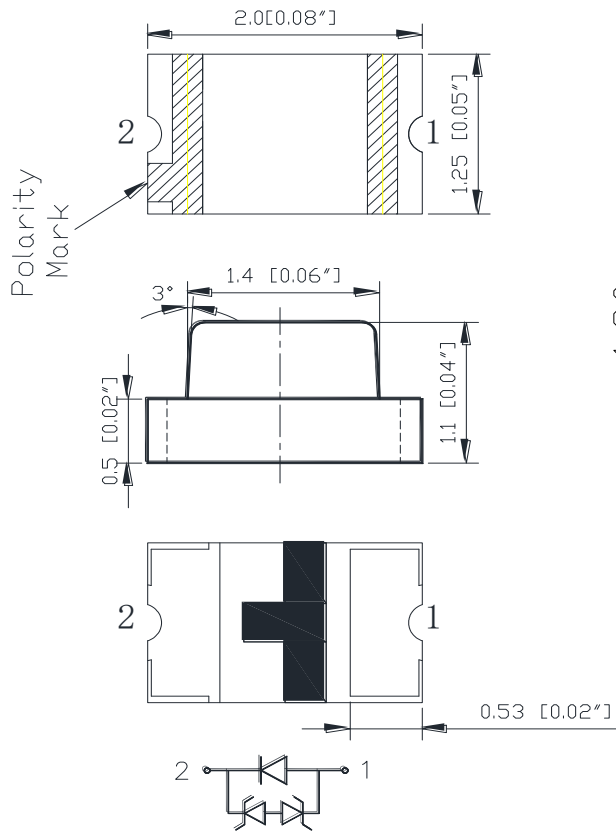
CBL0805A-ZBN-020mA

NOTE : Green Part

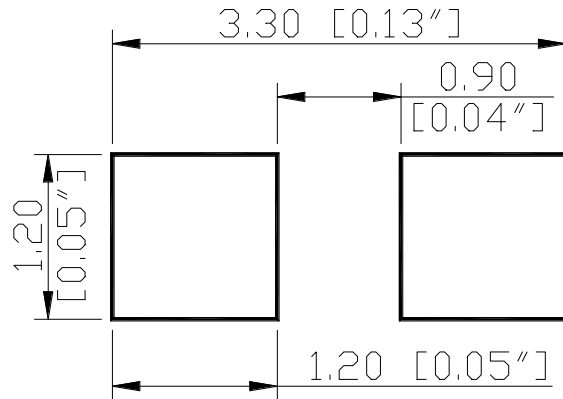
MAKER			CUSTOMER	
				
R&D	QA	Sales	Checked	Approved
				


Prepared	Checked	Approved
Rachel Lee	Sky Lin	Kenneth Wu

Package outlines



RECOMMEND PAD LAYOUT





ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
SENSITIVE DEVICES

ITEM	MATERIALS
Resin (mold)	Epoxy
Lens color	Water transparent
Dice	InGaN
Emitted color	Blue

NOTES:

1. All dimensions are in millimeters (inches);
2. Tolerances are $\pm 0.1\text{mm}$ (0.004inch) unless otherwise noted.

Absolute maximum ratings

($T_A=25^{\circ}\text{C}$)

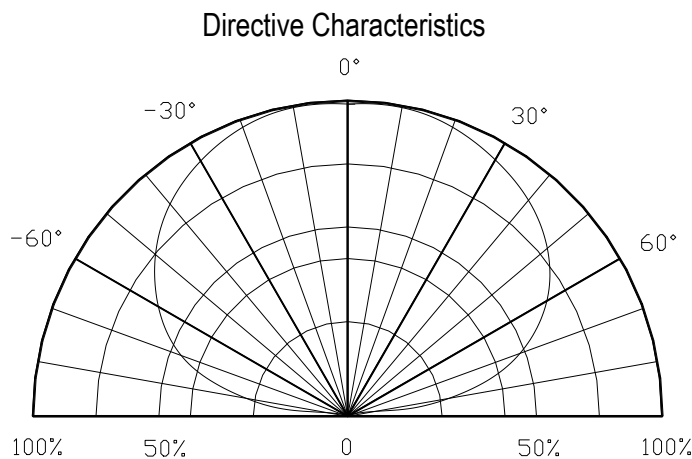
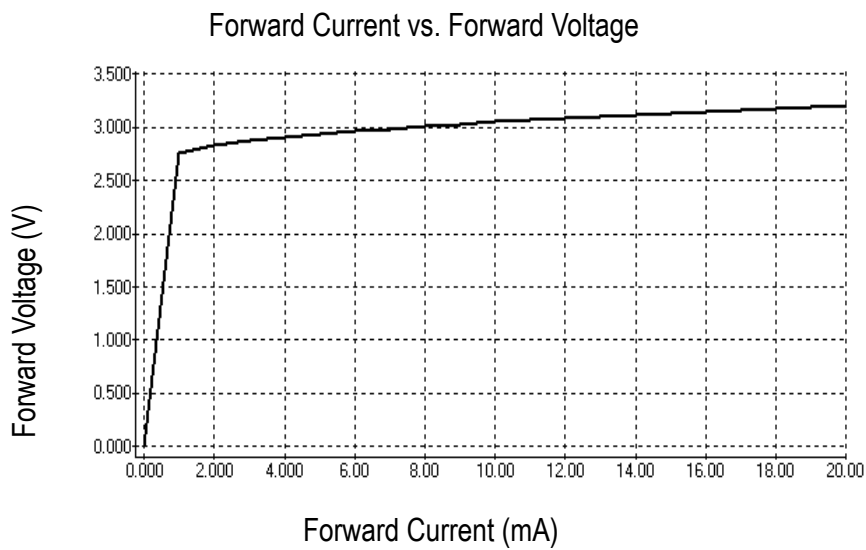
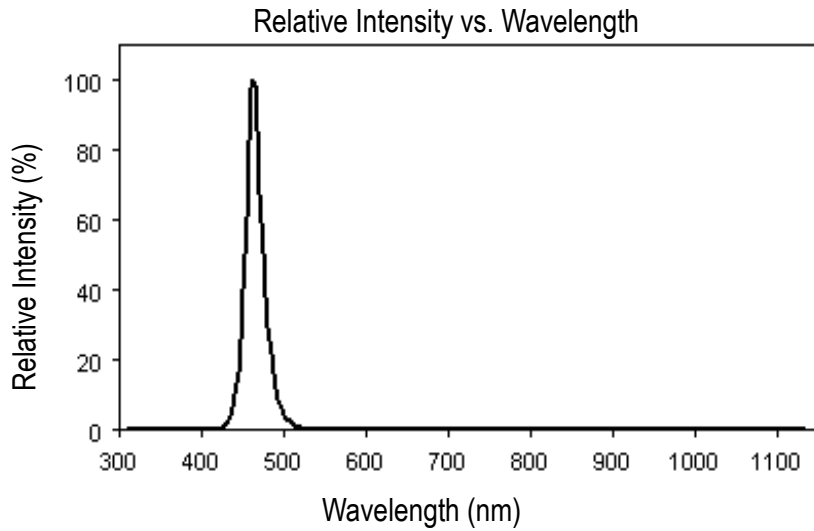
Parameter	Symbol	Value	Unit
Forward current	I_f	30	mA
Reverse voltage	V_r	5	V
Power dissipation	P_d	111	mW
Operating temperature range	T_{op}	-40 ~+80	$^{\circ}\text{C}$
Storage temperature range	T_{stg}	-40 ~+85	$^{\circ}\text{C}$
Peak pulsing current (1/8 duty f=1kHz)	I_{fp}	125	mA

Electro-optical characteristics

($T_A=25^{\circ}\text{C}$)

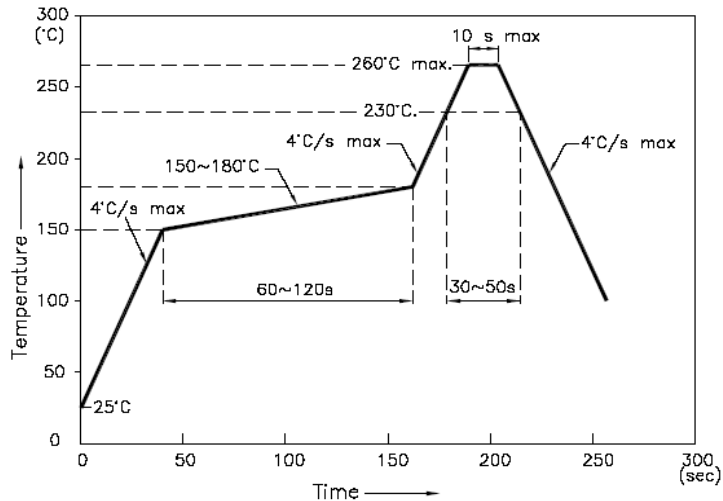
Parameter	Test Condition	Symbol	Value			Unit
			Min	Typ	Max	
Wavelength at peak emission	$I_f=20\text{mA}$	λ_{peak}	-	465	-	nm
Spectral half bandwidth	$I_f=20\text{mA}$	$\Delta\lambda$	-	25	-	nm
Dominant wavelength	$I_f=20\text{mA}$	λ_{dom}	460	465	470	nm
Forward voltage	$I_f=20\text{mA}$	V_f	2.8	3.1	3.7	V
Luminous intensity	$I_f=20\text{mA}$	I_v	63	100	200	mcd
Viewing angle at 50% I_v	$I_f=10\text{mA}$	$2\theta_{1/2}$	-	140	-	Deg
Reverse current	$V_r=5\text{V}$	I_r	-	-	10	μA

OPTICAL CHARACTERISTIC CURVES



Reflow Profile

■ Reflow Temp/Time



NOTES:

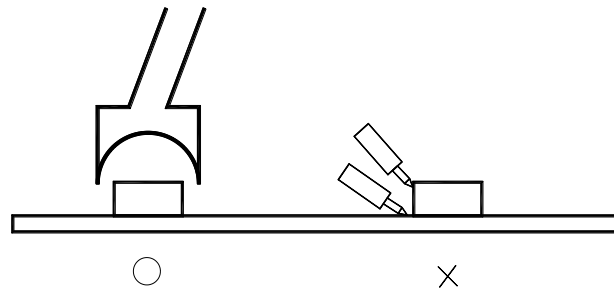
1. We recommend the reflow temperature $245^{\circ}\text{C} (\pm 5^{\circ}\text{C})$. the maximum soldering temperature should be limited to 260°C .
2. dont cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

■ Soldering iron

Basic spec is $\leq 5\text{sec}$ when 260°C . If temperature is higher, time should be shorter ($+10^{\circ}\text{C} \rightarrow -1\text{sec}$). Power dissipation of iron should be smaller than 20W, and temperatures should be controllable. Surface temperature of the device should be under 230°C .

■ Rework

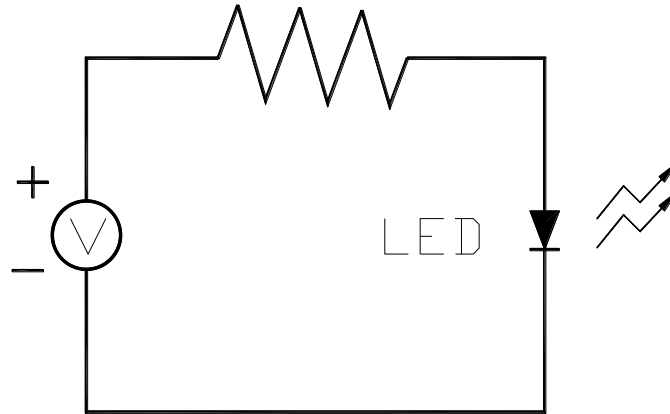
1. Customer must finish rework within 5 sec under 260°C .
2. The head of iron can not touch copper foil
3. Twin-head type is preferred.



■ Avoid rubbing or scraping the resin by any object, during high temperature, for example reflow 、 solder etc.

Test circuit and handling precautions

■ Test circuit



■ Handling precautions

1. Over-current-proof

Customer must apply resistors for protection; otherwise slight voltage shift will cause big current change (Burn out will happen).

2. Shelf life in sealed bag: 12 month at $5^{\circ}\text{C}\sim 30^{\circ}\text{C}$ and $< 60\%$ R.H;

3. After the package is Opened:

3.1. It is recommended to baking before the first use:

Baking condition:

a. $60\pm 5^{\circ}\text{C}$ x (24~48hrs) and $< 5\%$ RH, taped reel type ;

b. $110\pm 5^{\circ}\text{C}$ x (8~16hr), bulk type ;

3.2. The products should be used within a week and to be stored at $\leq 20\%$ R.H. with zip-lock sealed:

a. Baking is required before soldering when the pack is unsealed after 24hrs ;

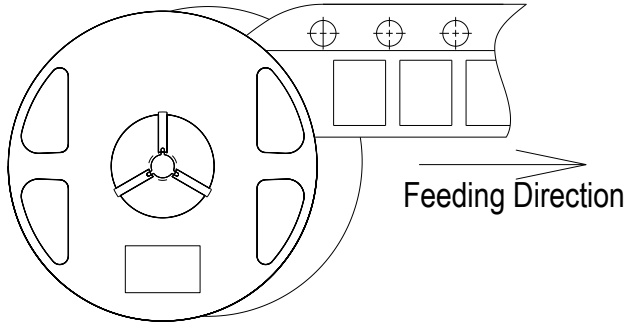
b. Baking condition as 3.1 baking condition.

Test items and results of reliability

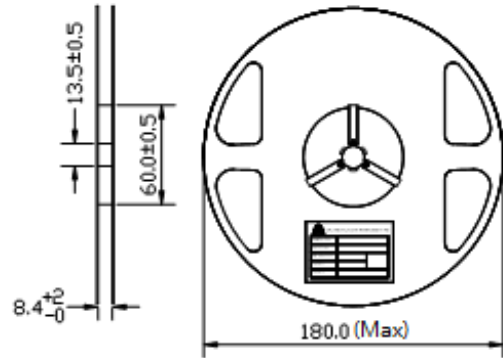
Type	Test Item	Test Conditions	Note	Number of Damaged
Environmental Sequence	Temperature Cycle	-20°C 30min ↑ ↓ 80°C 30min	100 cycle	0/22
	Thermal Shock	-20°C 15min ↑ ↓ 80°C 15min	100 cycle	0/22
	High Humidity Heat Cycle	30°C ↔ 65°C 90%RH 24hrs/1cycle	10 cycle	0/22
	High Temperature Storage	T _a =80°C	1000 hrs	0/22
	Humidity Heat Storage	T _a =60°C RH=90%	1000 hrs	0/22
	Low Temperature Storage	T _a =-30°C	1000 hrs	0/22
Operation Sequence	Life Test	T _a =25°C I _F =20mA	1000 hrs	0/22
	High Humidity Heat Life Test	60°C RH=90% I _F =10mA	500 hrs	0/22
	Low Temperature Life Test	T _a =-20°C I _F =20mA	1000 hrs	0/22

0805 Series SMD Chip LED Lamps Packaging Specifications

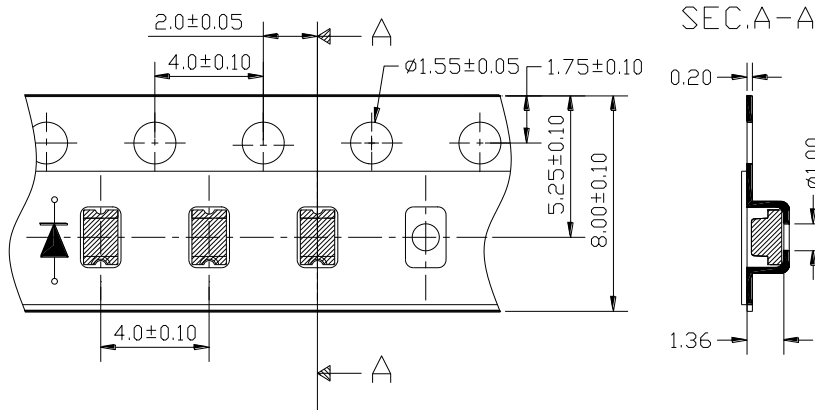
● Feeding Direction



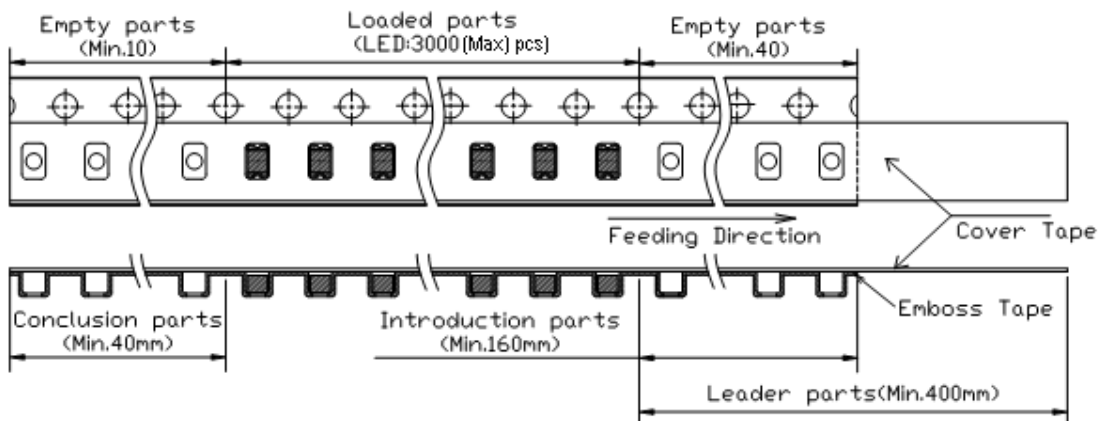
● Dimensions of Reel (Unit: mm)



● Dimensions of Tape (Unit: mm)



● Arrangement of

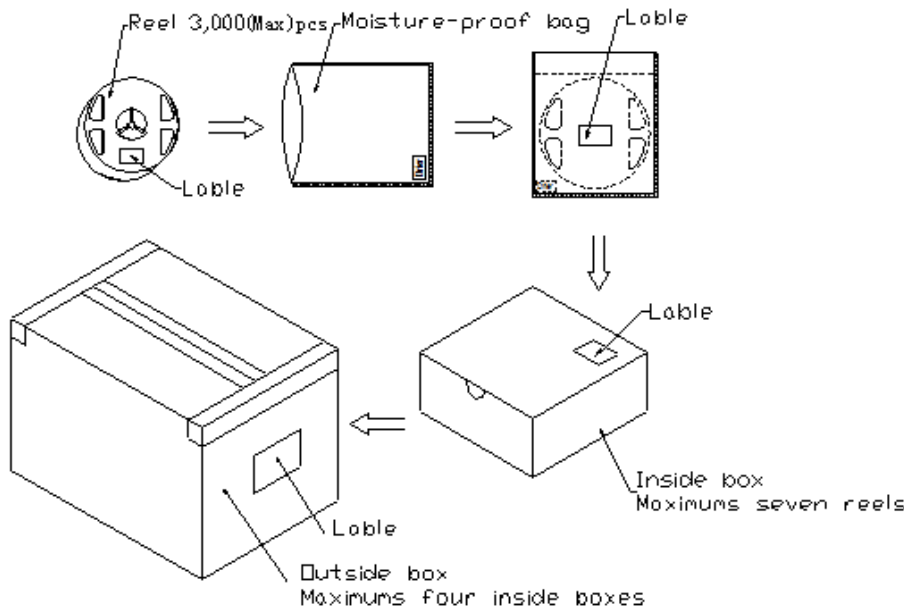


NOTES


1. Empty component pockets are sealed with top cover tape;
2. The maximum number of missing lamps is two;
3. The cathode is oriented towards the tape sprocket hole.
4. 3,000(Max)pcs/Reel

0805 Series SMD Chip LED Lamps Packaging Specifications

● Packaging specifications



Label

Solidlite Corp. 

P/N : _____

Lot : _____

Date: _____ Rank: _____

Q'ty : _____ QA : _____

NOTES:

Reeled products [numbers of products are 3,000(Max)pcs] packed in a seal off moisture-proof bag along with a desiccant one by one, Seven moisture-proof bag of maximums [total maximum number of products are 21,000(Max)pcs] packed in an inside box (size: about 238mm x about 194mm x about 102mm) and four inside boxes of maximums are put in the outside box (size: about 410mm x about 254mm x about 229mm) Together with buffer material, and it is packed. (Part No., Lot No., quantity should appear on the label on the moisture-proof bag, part No. And quantity should appear on the label on the cardboard box.) The number of the loading steps of outside box (cardboard box) has it to three steps.

Forward Voltage Rank Combination (IF=20mA)

Rank	Min.	Max.	Unit
f	2.8	3.1	V
g	3.1	3.4	
h	3.4	3.7	

Luminous Intensity Rank Combination (IF=20mA)

Rank	Min.	Max.	Unit
H	63	80	mcd
I	80	100	
J	100	125	
K	125	160	
L	160	200	

Dominant wavelength Rank Combination (IF=20mA)

Rank	Min.	Max.	Unit
E	460	462.5	nm
F	462.5	465	
G	465	467.5	
H	467.5	470	

Group Name on Label (Example DATA: gJF 20)

DATA: gJF 20	Vf(V)	Iv (mcd)	λ d (nm)	Test Condition
g→J→F→20	3.1~3.4	100~125	462.5~465	IF=20mA

* NOTE:

1. The tolerance of luminous intensity (Iv) is $\pm 15\%$.
2. The tolerance of dominant wavelength is $\pm 1.5\text{nm}$.
3. This specification is preliminary.